

## Alpha & Omega Semiconductor Product Reliability qualification Report

**AOZ8S513BDS-05, rev A** 

**Plastic Encapsulated Device** 

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This AOS product reliability report summarizes the qualification result for AOZ8S513BDS-05. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOZ8S513BDS-05 passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

## I. Reliability Stress Test Summary and Results

Test Item	Test Condition	Time Point	Total Sample Size	Number of Failures	Reference Standard
HTRB	Temp = 150°C , Vdd=100% of VRWMmax	1000 hrs	231 pcs	0	JESD22-A108
HAST	168hr 85°C / 85%RH + 3 cycle reflow@260°C (MSL 1)*	-	221 nos	0	JESD22-A113
	130°C , 85%RH, 33.3 psia, Vdd = 80% of VRWMmax	96 hrs	231 pcs	0	ESD22-A110
Autoclave	168hr 85°C / 85%RH + 3 cycle reflow@260°C (MSL 1)*	-	231 pcs	0	JESD22-A113
	121°C , 29.7psia, RH=100%	96 hrs	231 μcs	0	JESD22-A102
Temperature Cycle	168hr 85°C / 85%RH + 3 cycle reflow@260°C (MSL 1)*	-	221 nos	0	JESD22-A113
	-65°C to 150°C , air to air	1000 cycles	231 pcs	0	JESD22-A104

Note: The reliability data presents total of available generic data up to the published date.

## II. Reliability Evaluation

FIT rate (per billion): 15.26

MTTF = 7480 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

Failure Rate =  $Chi^2 \times 10^9 / [2 (N) (H) (Af)] = 15.26$ MTTF =  $10^9 / FIT = 7480$  years

Chi<sup>2</sup> = Chi Squared Distribution, determined by the number of failures and confidence interval

**N** = Total Number of units from burn-in tests

**H** = Duration of burn-in testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [Af] = Exp [Ea / k (1/Tj u - 1/Tj s)]

**Acceleration Factor ratio list:** 

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	259	87	32	13	5.64	2.59	1

<sup>\*:</sup> MSL (Moisture Sensitivity Level) 1 based on J-STD-020



**Tj s** = Stressed junction temperature in degree (Kelvin), K = C+273.16 **Tj u** =The use junction temperature in degree (Kelvin), K = C+273.16 **k** = Boltzmann's constant, 8.617164 X  $10^{-5}$ eV / K